Product/Process Change Notice - PCN 2361M -

Analog Devices, Inc. One Analog Way, Wilmington, MA01887, USA

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Wafer Size Change for MAX3158 Device
Publication Date:	15-Dec-2023
Effectivity Date:	*14-Mar-2024 (the earliest date that a customer could expect to receive changed material)*
Revision Description:	Initial Release.

Description Of Change:

Analog Devices Beaverton/USA is moving from current 6-inch wafer size (process S3) to 8-inch wafer size (process B3).

Note: B3 process qualification completed in 2010 and has been running in Beaverton fab since.

This is a wafer size change only.

Reason For Change:

Analog Devices Beaverton/USA fab is moving to the 8-inch process to ensure adequate capacity for supply continuity.

Impact of the change (positive or negative) on fit, form, function & reliability:

There are no changes to the form, fit, function, quality, or reliability of the device.

Product Identification (this section will describe how to identify the changed material):

Analog Devices maintains full traceability by device marking, packaging labels and shipment documents.

Summary of Supporting Information:

Qualification has been performed per Industry Standard Test Methods. See attached Qualification Results Summary.

Supporting Documents:

Attachment 1: Type: Qualification Report Summary

MFN_B3 Qual report.pdf

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	**Europe:**	**Japan:**	**Rest of Asia:**
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_ROA@analog.com

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Appendix A - Impacted items, see csv PN listing in PCN Zip file